

PCB Number: SV601095
PCB Rev: A

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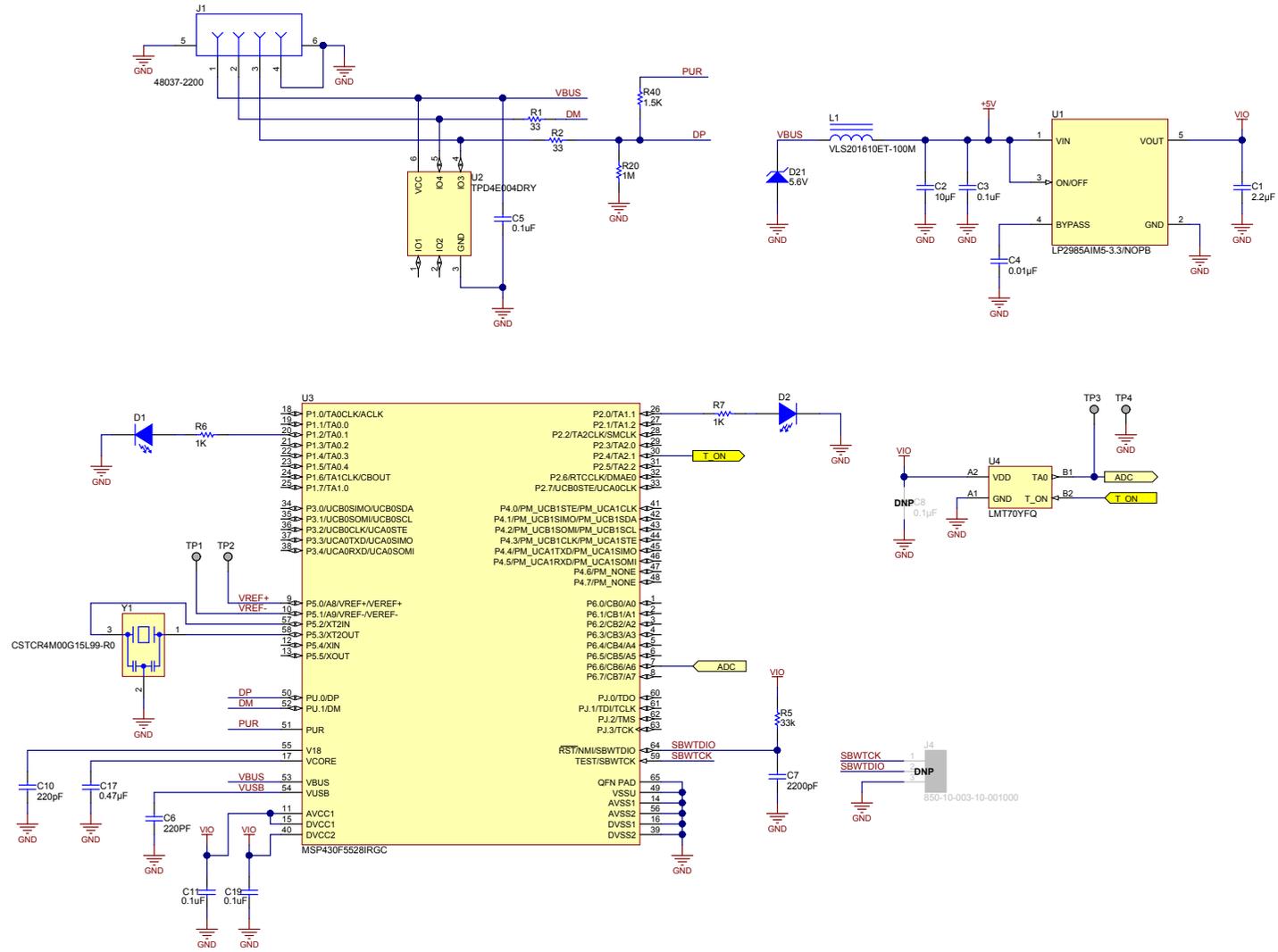
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Designed for Public Release	Mod. Date: 12/7/2014	
Number: SV601095	Rev: A	
SVN Rev: Not in version control	Assembly Variant: 001	Sheet Title: TIDA-00452 - Temperature Sensor for Wearable Dev
Drawn By:	File: SV601095A.SchDoc	Sheet 1 of 1
Engineer: Aaron Heng	Contact: http://www.ti.com/support	Size: B
		http://www.ti.com
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